

# El-27003: Electronics Devices and Circuits

## Lecture - 7

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### **LECTURE - 7**

Year: 2020-21

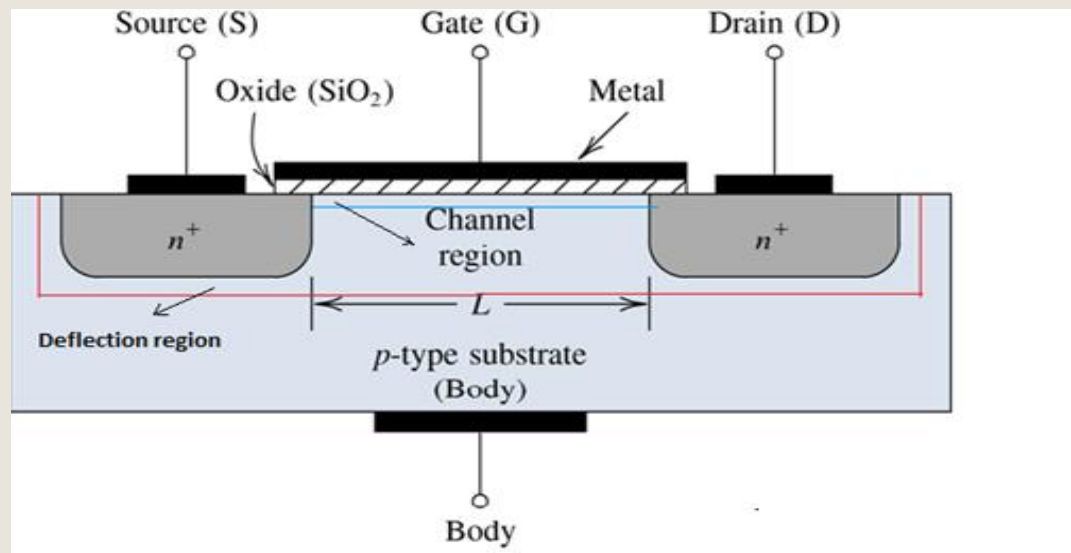
# Unit – 4 : MOS Transistor

- Today's class:
  1. Construction
  2. Types and symbols
  3. Operation-1

Construction:

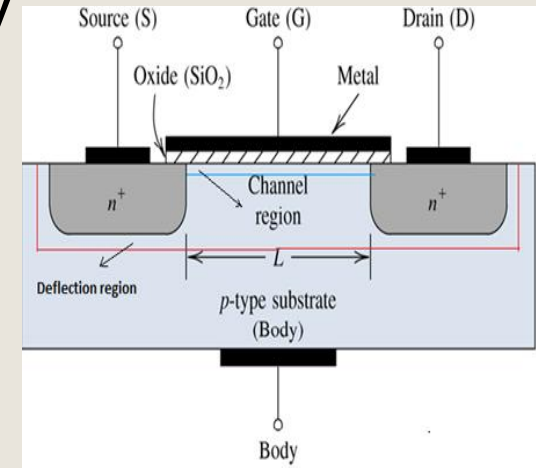
MOS Transistor also called as MOSFET stands for:

**M**etal **O**xide **S**emiconductor **F**ield **E**ffect **T**ransistor



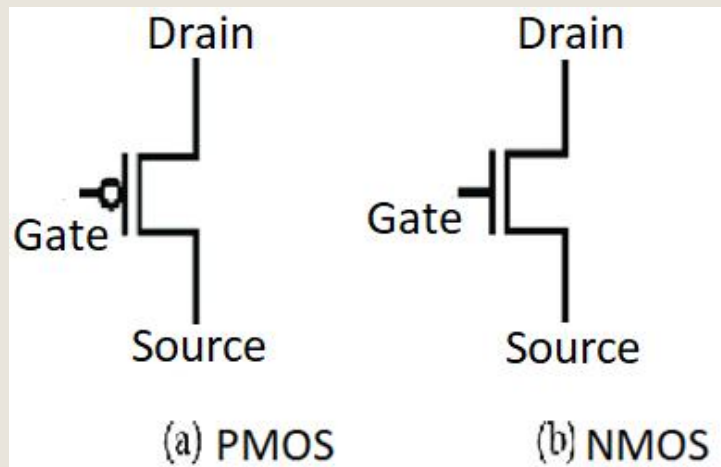
# MOS Construction

- MOS consists of p-type substrate/body
- In it two n-type semiconductor layers are alloyed as shown in fig.
- Over the substrate and between two n-type layers, a layer of Oxide( $\text{SiO}_2$ ) is deposited as shown in fig.
- A thin layer of Metal is deposited over this  $\text{SiO}_2$  layer.
- Contacts are taken out from this metal layer and from two n-layers as well as from substrate/body.
- These contacts are Source (S), Drain (D), Gate (G) and Body (B) as shown in fig.
- Such type of MOS transistor is called as n-channel MOS or simply nMOS.

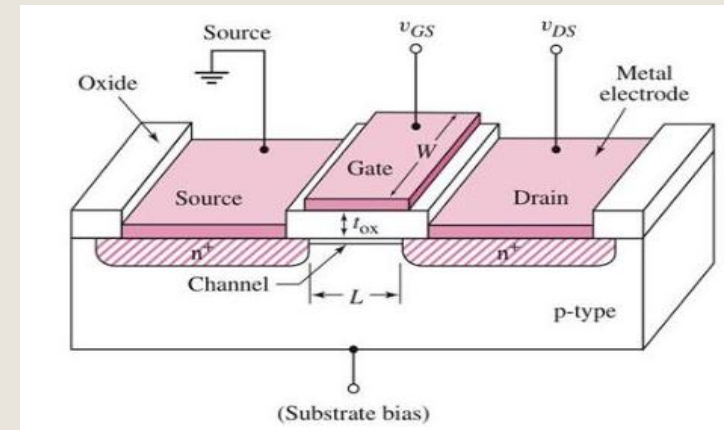
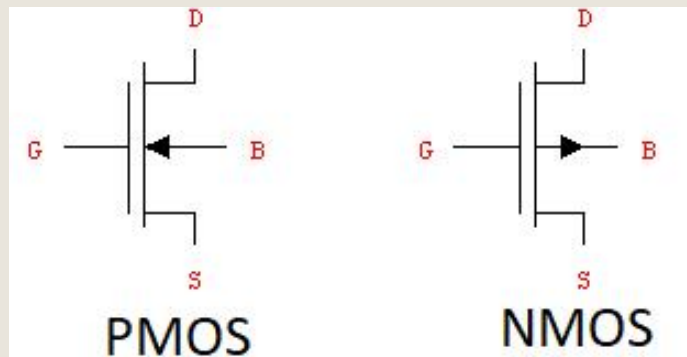


# MOS Transistor – Symbols & 3D view

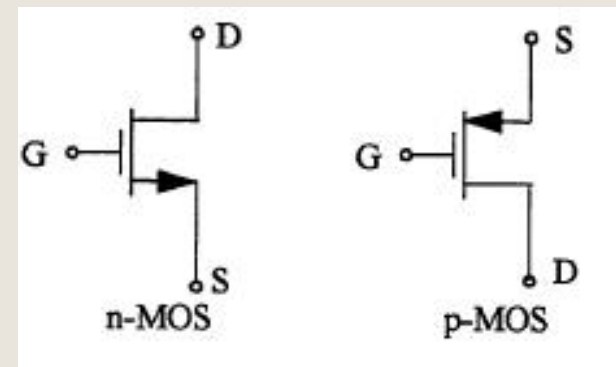
- Symbols:



OR



Now instead of metal polysilicon is used at gate.



# Operation – 1 (NMOS)

- Some important points:

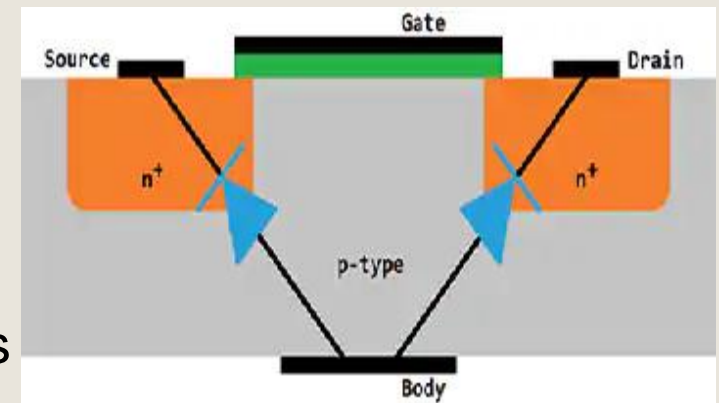
- Body of NMOS is always connected to ground/most negative.
- In NMOS drain (D) is connected to +ve terminal of battery and source (S) is connected to ground. ( $V_{DS}$ )
- In NMOS Gate (G) is connected to +ve terminal of battery w.r.t. source (S) ( $V_{GS}$ )

- Operation with No gate voltage

With NO bias voltage applied to Gate ( $V_{GS}=0$ ), two back to back diodes exist in series between drain and source.

One is n+ drain and p-type substrate and other is n+ source and p-type substrate.

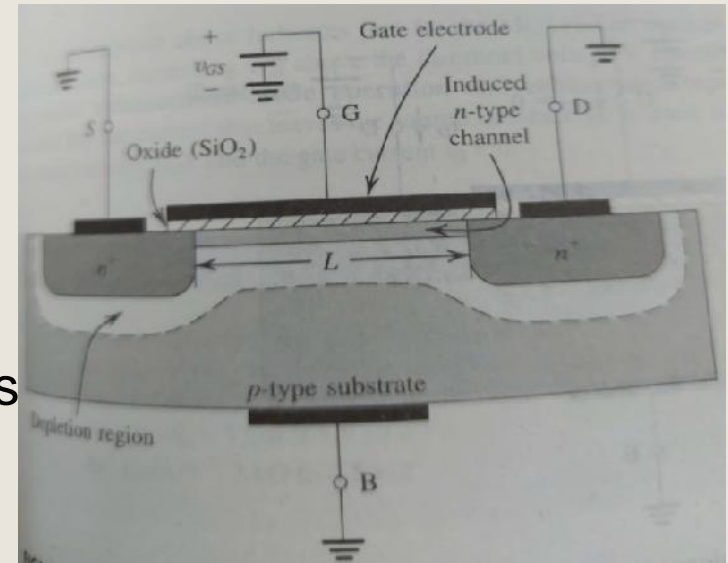
These back to back diodes prevent current conduction from drain to source when voltage  $V_{DS}$  is applied.



# Operation – 1 (NMOS)

- **Creating channel for current flow.**

- Consider fig shown.
- Here source and drain are grounded and +ve voltage is applied to the gate ( $V_{GS}$ ).
- The +ve voltage on gate causes the free holes to be repelled from region of substrate under the gate. These holes are pushed downward into substrate, leaving behind a carrier depletion region.
- Also, the +ve gate voltage attracts electrons from the n+ source and drain regions just below oxide layer. When sufficient number of electrons accumulate near the surface of substrate under gate, an n region is in effect created, connecting source and drain regions.
- Now if voltage is applied between drain and source ( $V_{DS}$ ), current flows through this induced n region called as n-channel.
- Note that n-channel is formed in p-substrate i.e. inverting substrate from p type to n type, this channel is called as **inversion** layer.



## Operation – 1 (NMOS)

- Threshold Voltage: The value of  $V_{GS}$  at which a sufficient number of mobile electrons accumulate in the channel region to form a conducting channel is called as threshold voltage and is denoted as  $V_t$
- $V_t$  for n channel MOS is positive and is controlled during device fabrication and is typically in range of 0.5v to 1v.

Time for Quiz

<https://forms.gle/JpQTS2qpQDbKvamE7>